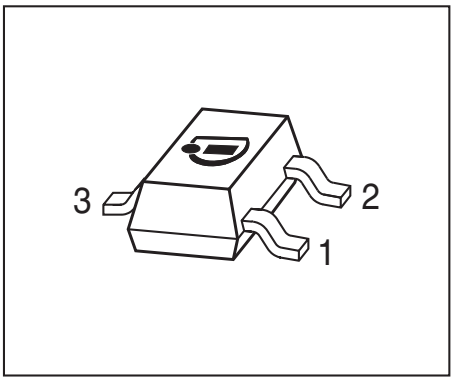
PNP Silicon AF Transistors



- For AF input stages and driver applications
- High current gain
- Low collector-emitter saturation voltage
- Low noise between 30 Hz and 15 kHz
- Complementary types: BCW60, BCX70 (NPN)
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101

Type	Marking	Pin Configuration			Package
BCW61A	BAs	1=B	2=E	3=C	SOT23
BCW61B	BBs	1=B	2=E	3=C	SOT23
BCW61C	BCs	1=B	2=E	3=C	SOT23
BCW61D	BDs	1=B	2=E	3=C	SOT23
BCX71G	BGs	1=B	2=E	3=C	SOT23
BCX71H	BHs	1=B	2=E	3=C	SOT23
BCX71J	BJs	1=B	2=E	3=C	SOT23
BCX71K	BKs	1=B	2=E	3=C	SOT23

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Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage BCW61... BCX71...	V_{CEO}	 32 45	V
Collector-base voltage BCW61... BCX71...	V_{CBO}	 32 45	
Emitter-base voltage	V_{EBO}	5	
Collector current	I_C	100	mA
Peak collector current, $t_p \leq 10$ ms	I_{CM}	200	
Peak base current	I_{BM}	200	
Total power dissipation- $T_S \leq 71$ °C	P_{tot}	330	mW
Junction temperature	T_j	150	-
Storage temperature	T_{stg}	-65 ... 150	°C

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point[1)]	R_{thJS}	≤ 240	K/W

[1]For calculation of R_{thJA} please refer to Application Note AN077 (Thermal Resistance Calculation)

Electrical Characteristics at T_A = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage	$V_{(BR)CEO}$				V
I_C = 10 mA, I_B = 0 , BCW61...		32	-	-	
I_C = 10 mA, I_B = 0 , BCX71...		45	-	-	
Collector-base breakdown voltage	$V_{(BR)CBO}$				
I_C = 10 µA, I_E = 0 , BCW61...		32	-	-	
I_C = 10 µA, I_E = 0 , BCX71...		45	-	-	
Emitter-base breakdown voltage I_E = 1 µA, I_C = 0	$V_{(BR)EBO}$	5	-	-	
Collector-base cutoff current	I_{CBO}				µA
V_{CB} = 32 V, I_E = 0		-	-	0.02	
V_{CB} = 45 V, I_E = 0		-	-	0.02	
V_{CB} = 32 V, I_E = 0 , T_A = 150 °C, BCW61...		-	-	20	
V_{CB} = 45 V, I_E = 0 , T_A = 150 °C, BCX71...		-	-	20	
Emitter-base cutoff current V_{EB} = 4 V, I_C = 0	I_{EBO}	-	-	20	nA
DC current gain[1)]	h_{FE}				-
I_C = 10 µA, V_{CE} = 5 V, h_{FE}-grp. A/G		20	140	-	
I_C = 10 µA, V_{CE} = 5 V, h_{FE}-grp. B/H		30	200	-	
I_C = 10 µA, V_{CE} = 5 V, h_{FE}-grp. C/J		40	300	-	
I_C = 10 µA, V_{CE} = 5 V, h_{FE}-grp. D/K		100	460	-	
I_C = 2 mA, V_{CE} = 5 V, h_{FE}-grp. A/G		120	170	220	
I_C = 2 mA, V_{CE} = 5 V, h_{FE}-grp. B/H		180	250	310	
I_C = 2 mA, V_{CE} = 5 V, h_{FE}-grp. C/J		250	350	460	
I_C = 2 mA, V_{CE} = 5 V, h_{FE}-grp. D/K		380	500	630	
I_C = 50 mA, V_{CE} = 1 V, h_{FE}-grp. A/G		60	-	-	
I_C = 50 mA, V_{CE} = 1 V, h_{FE}-grp. B/H		80	-	-	
I_C = 50 mA, V_{CE} = 1 V, h_{FE}-grp. C/J		100	-	-	
I_C = 50 mA, V_{CE} = 1 V, h_{FE}-grp. D/K		110	-	-	

DC Electrical Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Collector-emitter saturation voltage[1)]	V_{CEsat}				V
I_C = 10 mA, I_B = 0.25 mA		-	0.12	0.25	
I_C = 50 mA, I_B = 1.25 mA		-	0.2	0.55	
Base emitter saturation voltage[1)]	V_{BEsat}				
I_C = 10 mA, I_B = 0.25 mA		-	0.7	0.85	
I_C = 50 mA, I_B = 1.25 mA		-	0.83	1.05	
Base-emitter voltage[1)]	$V_{BE(ON)}$				
I_C = 10 µA, V_{CE} = 5 V		-	0.52	-	
I_C = 2 mA, V_{CE} = 5 V		0.55	0.65	0.75	
I_C = 50 mA, V_{CE} = 1 V		-	0.78	-	

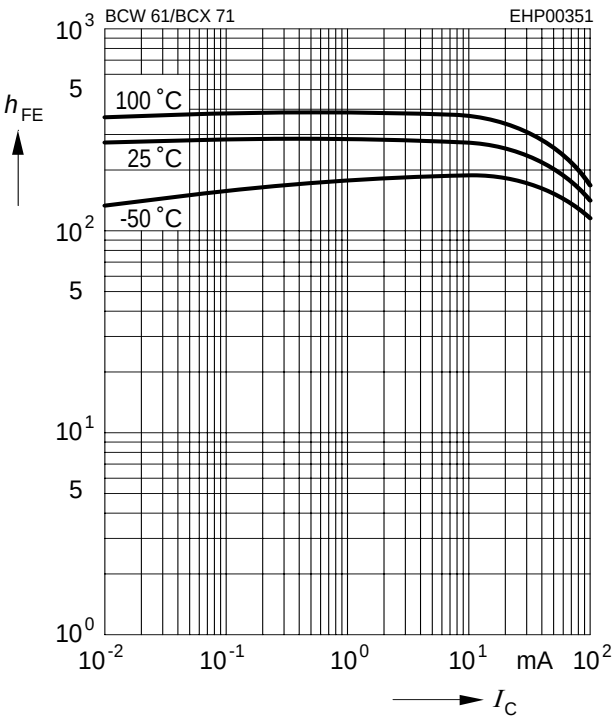
[1]Pulse test: t < 300µs; D < 2%

AC Characteristics

Transition frequency I_C = 20 mA, V_{CE} = 5 V, f = 100 MHz	f_T	-	250	-	MHz
Collector-base capacitance V_{CB} = 10 V, f = 1 MHz	C_{cb}	-	1.5	-	pF
Emitter-base capacitance V_{EB} = 0.5 V, f = 1 MHz	C_{eb}	-	8	-	
Short-circuit input impedance	h_{11e}				kΩ
I_C = 2 mA, V_{CE} = 5 V, f = 1 kHz, h_{FE}-grp. A/B		-	2.7	-	
I_C = 2 mA, V_{CE} = 5 V, f = 1 kHz, h_{FE}-grp. B/H		-	3.6	-	
I_C = 2 mA, V_{CE} = 5 V, f = 1 kHz, h_{FE}-grp. C/J		-	4.5	-	
I_C = 2 mA, V_{CE} = 5 V, f = 1 kHz, h_{FE}-grp. D/K		-	7.5	-	
Open-circuit reverse voltage transf. ratio	h_{12e}				10^{-4}
I_C = 2 mA, V_{CE} = 5 V, f = 1 kHz, h_{FE}-grp. A/B		-	1.5	-	
I_C = 2 mA, V_{CE} = 5 V, f = 1 kHz, h_{FE}-grp. B/H		-	2	-	
I_C = 2 mA, V_{CE} = 5 V, f = 1 kHz, h_{FE}-grp. C/J		-	2	-	
I_C = 2 mA, V_{CE} = 5 V, f = 1 kHz, h_{FE}-grp. D/K		-	3	-	
Short-circuit forward current transf. ratio	h_{21e}				-
I_C = 2 mA, V_{CE} = 5 V, f = 1 kHz, h_{FE}-grp. A/B		-	200	-	
I_C = 2 mA, V_{CE} = 5 V, f = 1 kHz, h_{FE}-grp. B/H		-	260	-	
I_C = 2 mA, V_{CE} = 5 V, f = 1 kHz, h_{FE}-grp. C/J		-	330	-	
I_C = 2 mA, V_{CE} = 5 V, f = 1 kHz, h_{FE}-grp. D/K		-	520	-	
Open-circuit output admittance	h_{22e}				µS
I_C = 2 mA, V_{CE} = 5 V, f = 1 kHz, h_{FE}-grp. A/B		-	18	-	
I_C = 2 mA, V_{CE} = 5 V, f = 1 kHz, h_{FE}-grp. B/H		-	24	-	
I_C = 2 mA, V_{CE} = 5 V, f = 1 kHz, h_{FE}-grp. C/J		-	30	-	
I_C = 2 mA, V_{CE} = 5 V, f = 1 kHz, h_{FE}-grp. D/K		-	50	-	
Noise figure I_C = 200 µA, V_{CE} = 5 V, f = 1 kHz, Δf = 200 Hz, R_S = 2 kΩ, h_{FE}-grp. A/K	F	-	2	-	dB

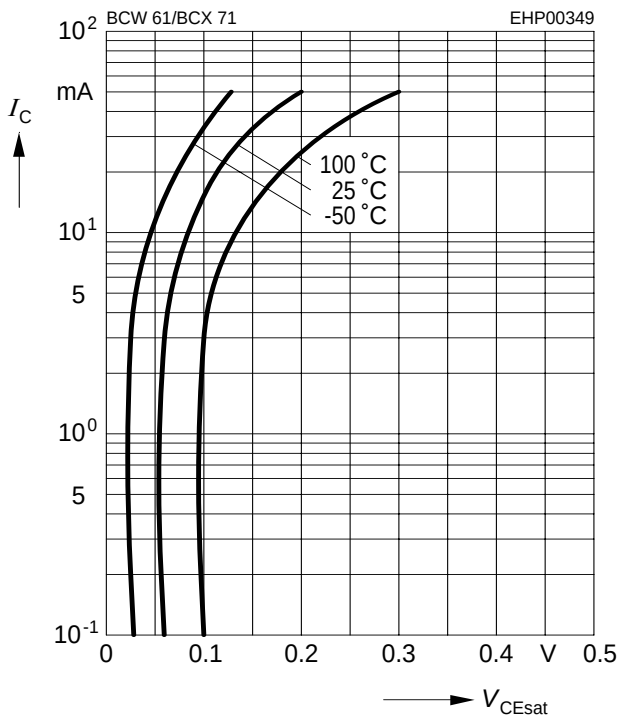
DC current gain $h_{FE} = f(I_C)$

V_{CE} = 5 V



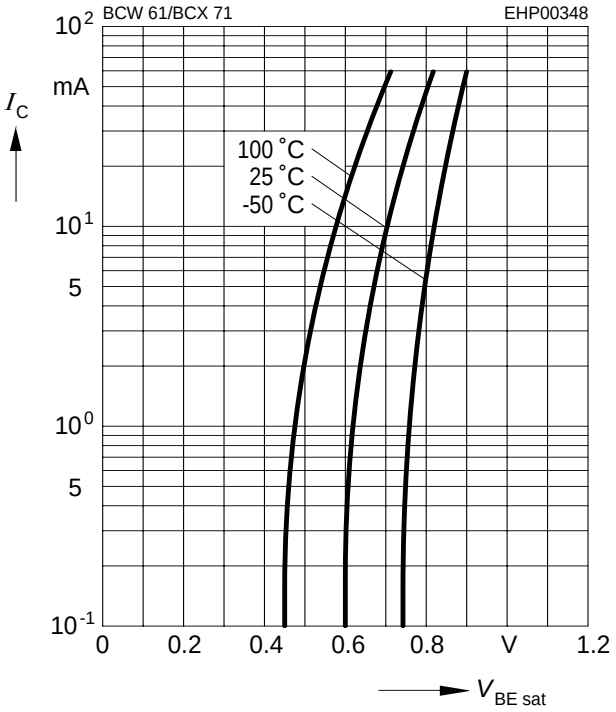
Collector-emitter saturation voltage

$I_C = f(V_{CEsat})$, h_{FE} = 40



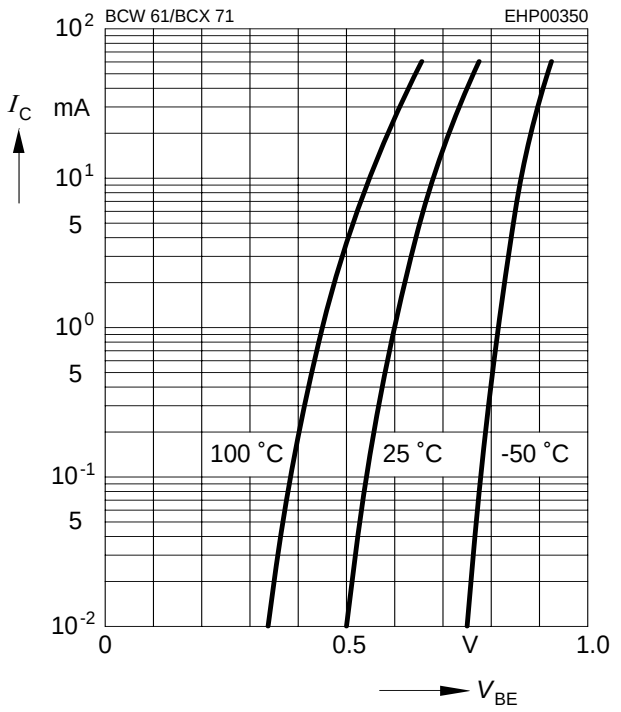
Base-emitter saturation voltage

$I_C = f(V_{BEsat})$, h_{FE} = 40



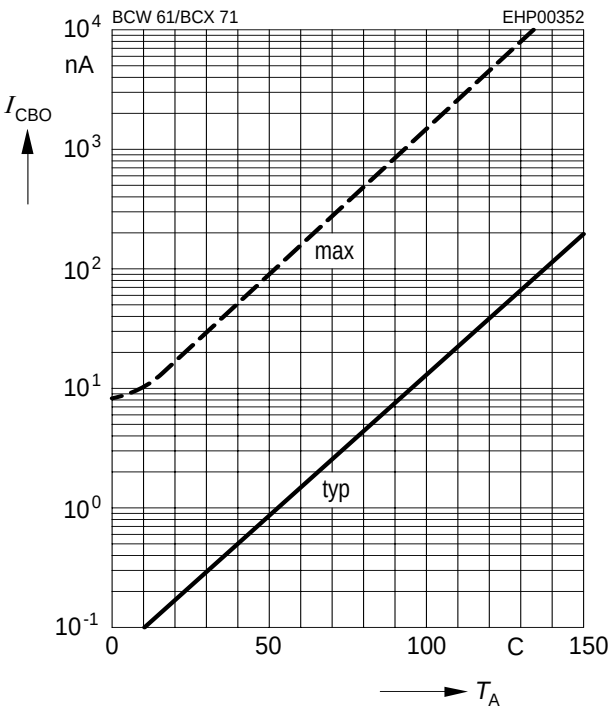
Collector current $I_C = f(V_{BE})$

V_{CE} = 5 V



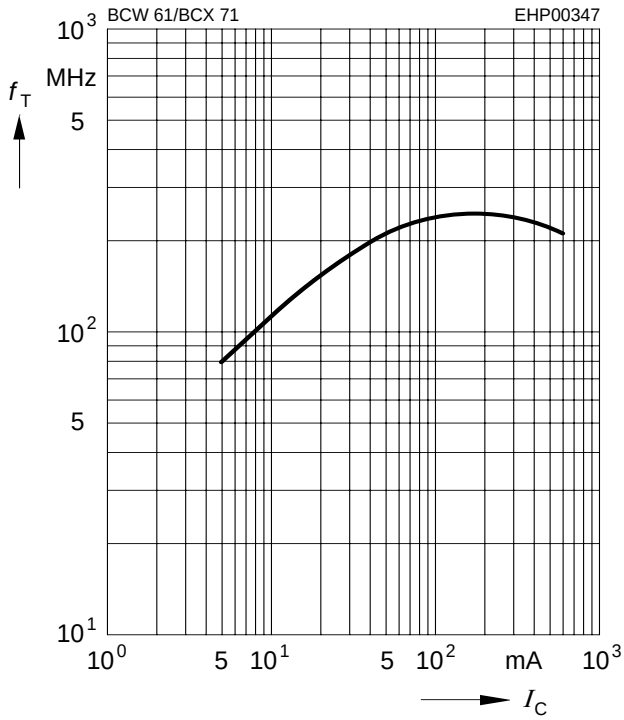
Collector cutoff current $I_{CBO} = f(T_A)$

$V_{CB} = V_{CEmax}$



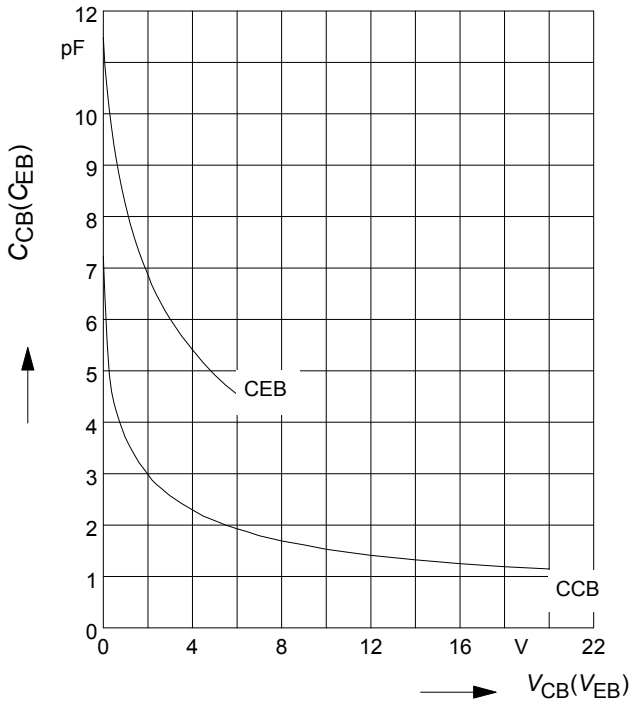
Transition frequency $f_T = f(I_C)$

V_{CE} = parameter in V, f = 2 GHz

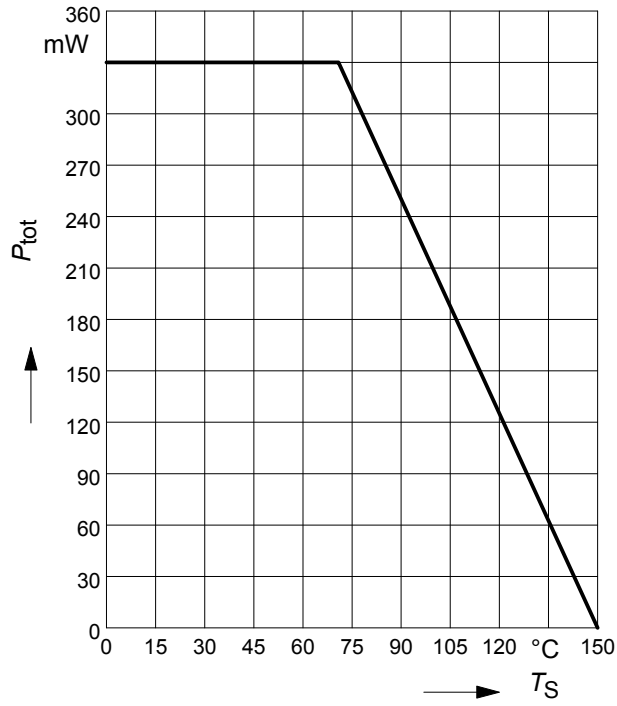


Collector-base capacitance $C_{cb} = f(V_{CB})$

Emitter-base capacitance $C_{eb} = f(V_{EB})$

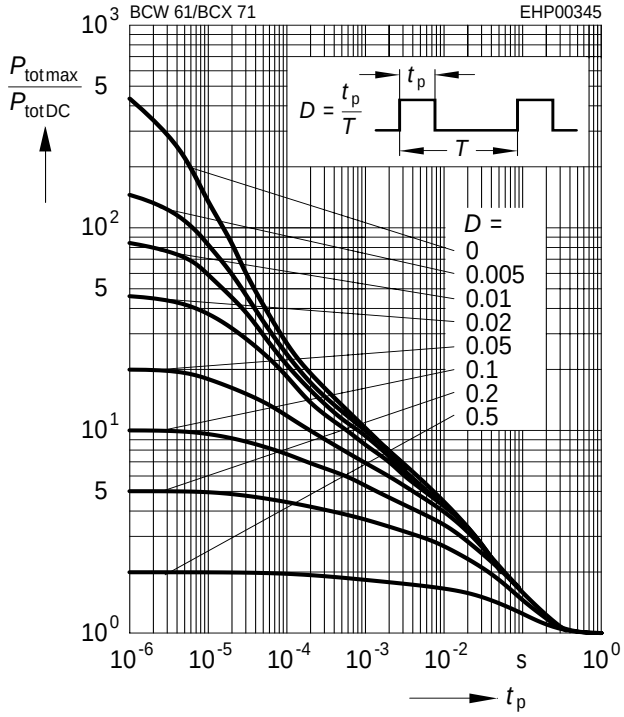


Total power dissipation $P_{tot} = f(T_S)$



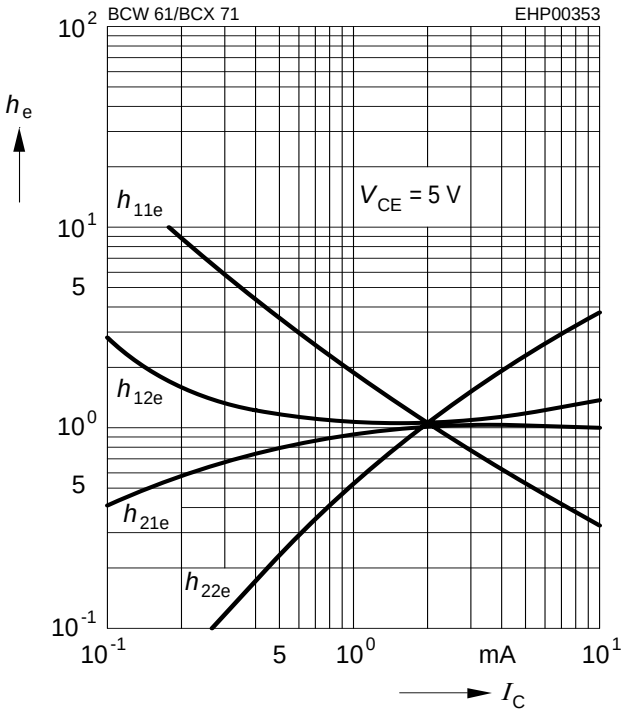
Permissible Pulse Load

$P_{totmax}/P_{totDC} = f(t_p)$



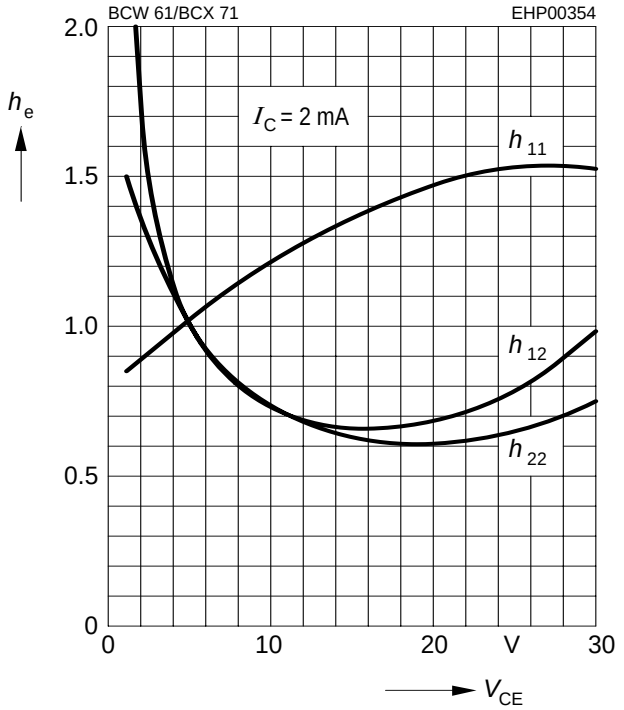
h parameter $h_e = f(I_C)$ normalized

V_{CE} = 5V



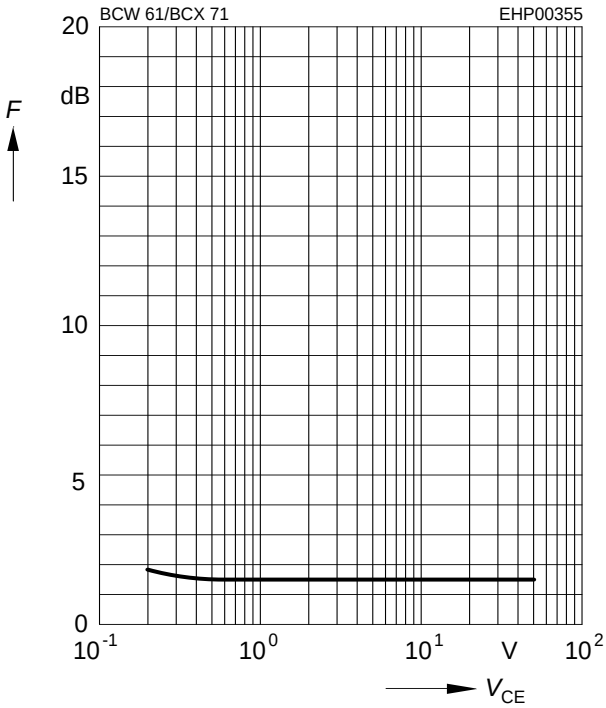
h parameter $h_e = f(V_{CE})$ normalized

I_C = 2mA



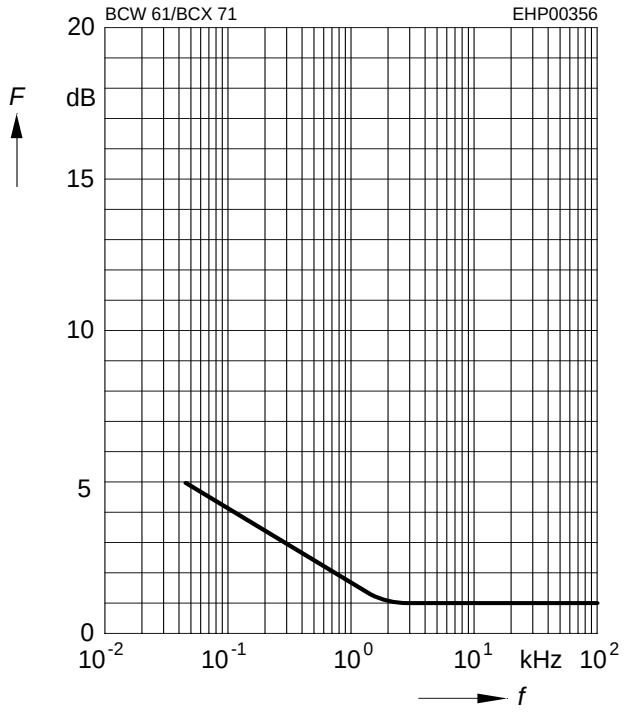
Noise figure $F = f(V_{CE})$

I_C = 0.2mA, R_S = 2kΩ , f = 1kHz



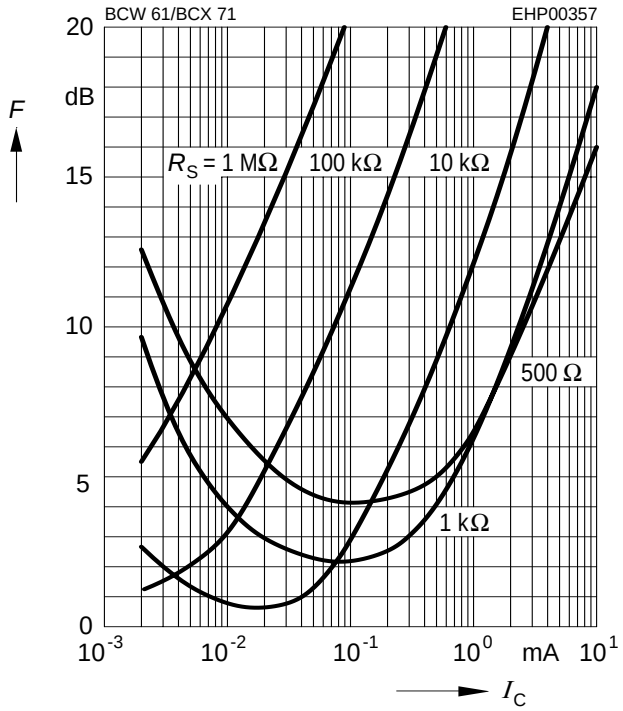
Noise figure $F = f(f)$

V_{CE} = 5V, $Z_S = Z_{Sopt}$



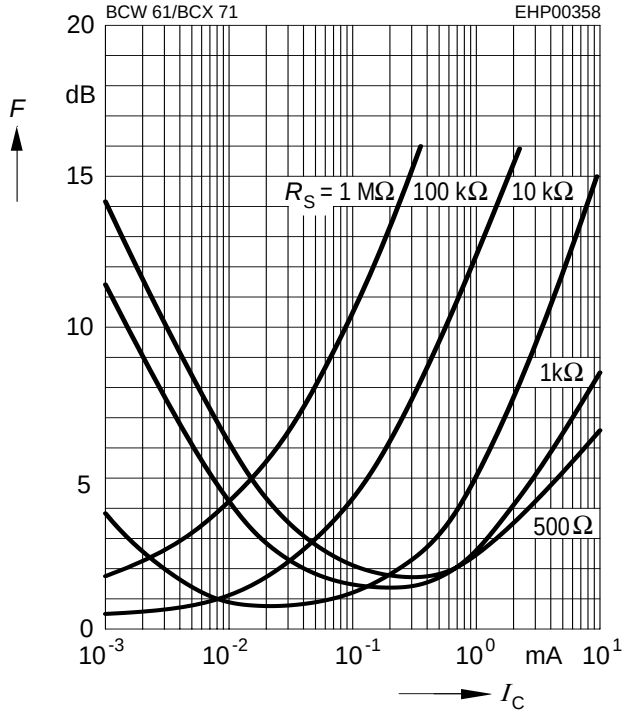
Noise figure $F = f(I_C)$

V_{CE} = 5V, f = 120Hz



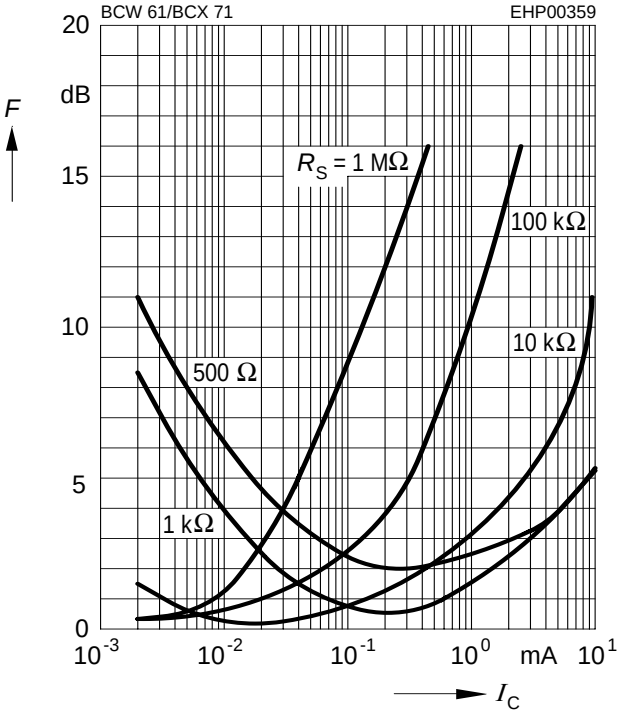
Noise figure $F = f(I_C)$

V_{CE} = 5V, f = 1kHz

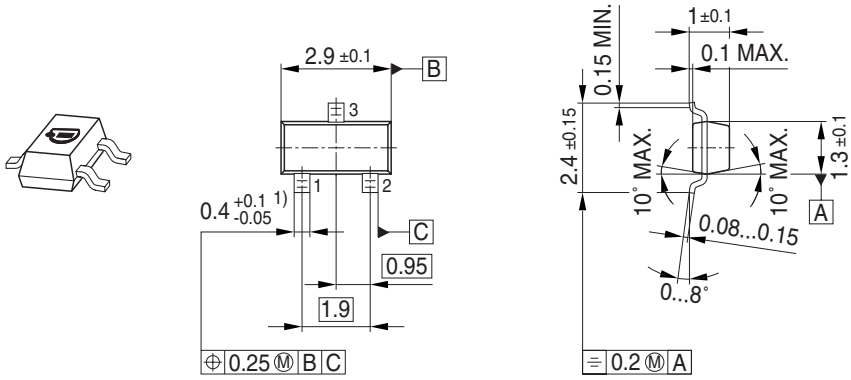


Noise figure $F = f(I_C)$

V_{CE} = 5V, f = 10kHz

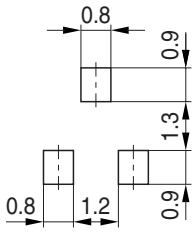


Package Outline

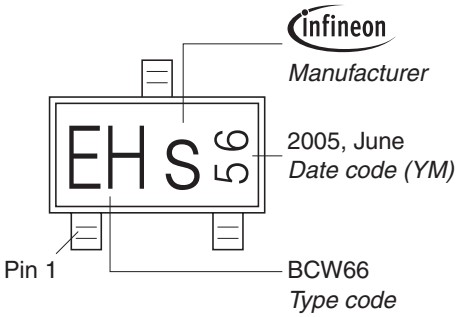


1) Lead width can be 0.6 max. in dambar area

Foot Print

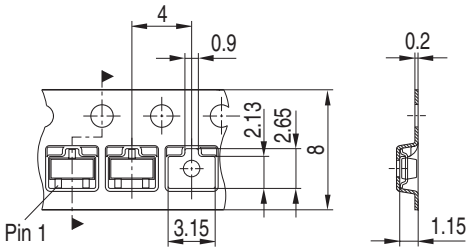


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



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